

# ISMP 2020

The 19<sup>th</sup> International Symposium on Microelectronics and Packaging  
November 11-13, 2020, Busan, Korea

## INVITATION

It is our pleasure to announce that the 19th International Symposium on Microelectronics and Packaging (ISMP 2020) will be held at Busan, Korea, on November 11-13, 2020. This international conference is organized by KMEPS (the Korean Microelectronics and Packaging Society), and will address comprehensive coverage of recent advances in electronic packaging process and materials. This conference will be proceed with oral and poster presentations on the latest electronic packaging technologies for three days. This will provide an excellent opportunity for researchers and engineers of academic institutes and industries to discuss recent advances and new technology directions. We cordially invite you to submit abstracts for the conference, and look forward to welcoming you in Korea.

## SYMPOSIUM TOPICS

ISMP 2020 will include all fundamental and applied sciences and technologies related to the fields of electronic materials, devices, and packaging. Topics may include from, but are not limited to, the following areas:

- Advanced Packaging Technologies
- Emerging Process for Interconnects and Packaging
- Power Electronic Packaging
- Wearable and Printed Electronics
- Reliability of Electronic Devices and Systems
- Electronic Materials for Interconnects and Packaging
- PCB, Solder, and Assembly Process
- Sensors, LED, and Emerging Packaging Technology
- MEMS/NEMS Packaging and Applications
- Design Tools and Modeling

\* It should be noted that the program committee reserves the right to make a final decision on the session and presentation type of oral or poster regardless of author's preference.

## IMPORTANT DATES

Submission of Abstract	July 15, 2020
Notification of Acceptance	August 31, 2020
Pre-registration	October 30, 2020
Symposium	November 11-13, 2020
Submission of Final Manuscript	December 31, 2020

## CONFERENCE LANGUAGE

The official language of the symposium is English.

## SYMPOSIUM SECRETARIAT (CONTACT)

Ms. Min-Jin Kim (KMEPS) Tel: +82-2-538-0962, Mobile: +82-10-5205-8213, Fax: +82-2-538-0963 E-mail: [kmeps@ismp2020.org](mailto:kmeps@ismp2020.org)  
Ms. So-Yoon Park (KMEPS) Tel: +82-2-538-0962, Fax: +82-2-538-0963 E-mail: [kmeps@kmeps.or.kr](mailto:kmeps@kmeps.or.kr)  
Visit the ISMP 2020 website ([www.ismp2020.org](http://www.ismp2020.org)) for additional symposium information.

Organized by The Korean Microelectronics and Packaging Society (KMEPS)